

Product Data Sheet

flexilink b-t-b, 25 mm height,
Part No. 990-52XNN250-110



Illustration similar



Parallel



Press-fit



Power



Rugged

- 25 mm height
- for two-stage press-in operation
- 1 - 3 contact rows
- space & cost saving
- part number key: X = number of rows, NN = contacts per row
- For requests please contact our sales department.



» to product on www.ept.de



» to product group flexilink board-to-board connector

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Technical Specifications

Basics

No. of Contacts	2 - 90 (max. 30 per row)
Termination Technology	Press-fit
Board-to-Board Distance	25 mm
Operating Temperature Range	-40°C to +125°C

Material

Insulator Material	PBT
CTI value <i>IEC 60112</i>	250
Contact Material	Copper alloy
Plating	Sn

Mechanical

Pitch	2.54 mm or individually assembled
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Electrical

Operational Current	max. 11 A at 20°C per pin (1x10 pins, height 15 mm) max. 7 A at 20°C per pin (2x10 pins, height 15 mm) max. 6 A at 20°C per pin (3x10 pins, height 15 mm)
Contact Resistance	<5 mΩ
Clearance and Creepage	min. 0.44 mm / 0.57 mm (within the row) min. 1.94 / 2.07 mm (between the rows)

Processing

Assembly	manual / semi-automatic / fully automatic
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Approval / Compliance

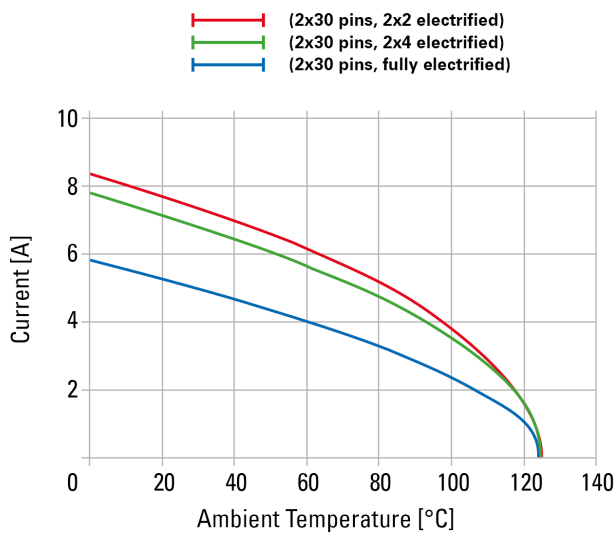
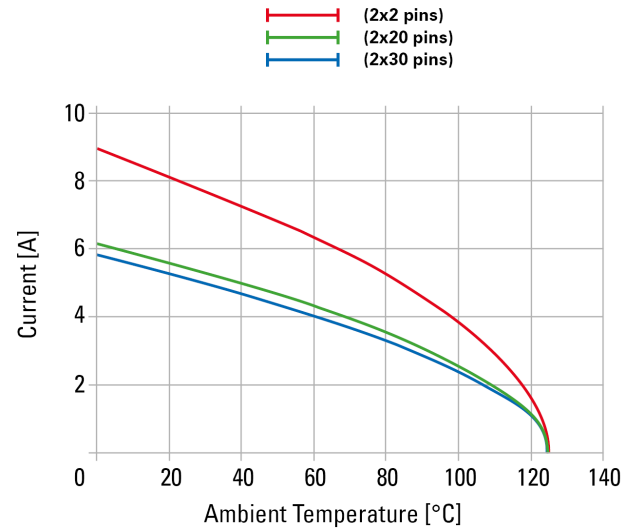
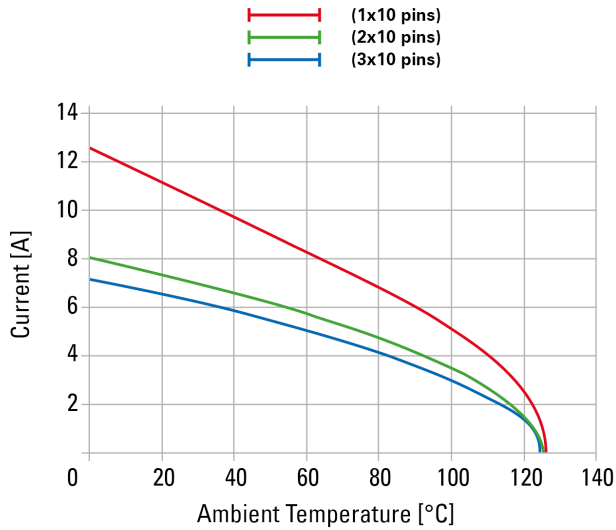
UL file	E130314
Environment	RoHS compliant

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Derating Diagram



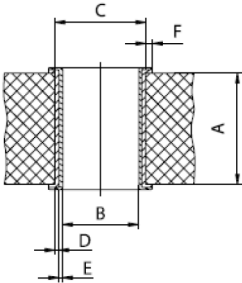
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
Nominal Hole	Ø 1.0 mm
A PCB Thickness	min 1.4 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	Ø 1.0 mm
A PCB Thickness	min 1.4 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	pure Cu printed circuit boards
Nominal Hole	Ø 1.0 mm
A PCB Thickness	min 1.4 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	OSP, z.B. GLICOAT-SMD (F2) with 0.12 - 0.15 µm
F Annular Ring	min. 0.1 mm

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Modifications

Available on request

- other pin configurations

Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)